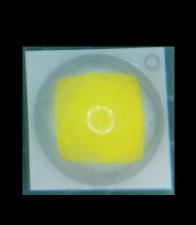




# Bridgelux® SMD 3535 2W 3V

**Product Data Sheet DS890** 



## Introduction

#### Feature

- Package: SMT ceramic package with silicone lens
- Lumen maintenance: Test results according to IESNA LM-80 available
- ESD8kV HBM. JEDEC-JS-001-HBM and JEDEC-JS-001-2012
- Operates at a maximum current of up to 1.5A
- · Hot binning @ 85 °C

## **Application**

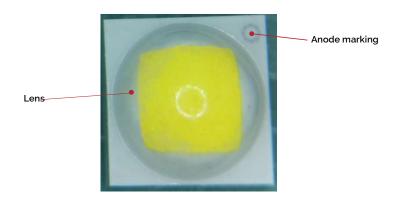
- Outdoor Lighting: Street Light, Tunnel Light, Security Light, Area Light, Stadium/Arena Light
- · Industrial Lighting: High Bay Light, Low Bay Light
- Consumer Lighting: Torch Light

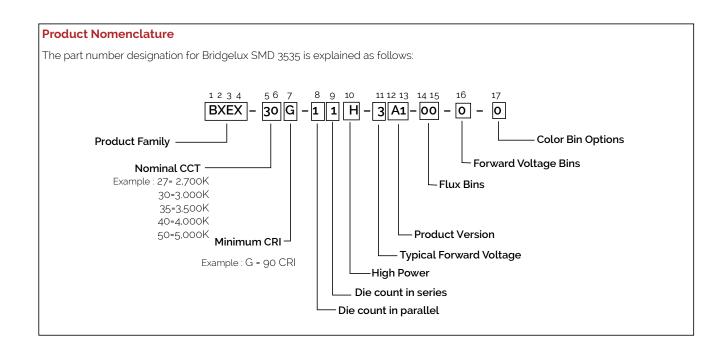
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# Product Feature Map

Bridgelux SMD LED products come in industry standard package sizes and follow ANSI binning standards. These LEDs are optimized for cost and performance, helping to ensure highly competitive system lumen per dollar performance while addressing the stringent efficacy and reliability standards required for modern lighting applications.





## **Product Selection Guide**

The following product configurations are available:

**Table 1:** Selection Guide, Pulsed Measurement Data at 700mA (T<sub>i</sub>=T<sub>sn</sub>=25°C)

Part Number <sup>16</sup>	Nominal CCT <sup>2</sup>	CRI3.5		al CCT <sup>2</sup> CRI <sup>3,5</sup> Drive		Nominal Forward Voltage <sup>4,5</sup> Drive Current (V)			Typical Pulsed	Typical Power	Typical Effica-
	(K)		(mA)	Min	Typical	Max	Flux (lm) <sup>4,5</sup>	(W)	cy (lm/W)		
BXEX-27G-11H-3A1-00-0-0	2700	90	700	2.8	3.0	3.2	218	2.1	104		
BXEX-30G-11H-3A1-00-0-0	3000	90	700	2.8	3.0	3.2	223	2.1	106		
BXEX-35G-11H-3A1-00-0-0	3500	90	700	2.8	3.0	3.2	239	2.1	114		
BXEX-40G-11H-3A1-00-0-0	4000	90	700	2.8	3.0	3.2	257	2.1	122		
BXEX-50G-11H-3A1-00-0-0	5000	90	700	2.8	3.0	3.2	257	2.1	122		
BXEX-68G-11H-3A1-00-0-0	6800	90	700	2.8	3.0	3.2	239	2.1	114		

**Table 2:** Selection Guide, Pulsed Test Performance  $(T_{sp} = 85^{\circ}C)^{7.8}$ 

Part Number¹⁵	Nominal CCT <sup>2</sup>	CRI3.5	Nominal Drive Cur-	F	orward Voltag (V)	e <sup>5</sup>	Typical Pulsed	Typical Power	Typical Efficacy
raitramber	(K)	OI.	rent (mA)	Min	Typical	Max	Flux (lm)⁵	(W)	(lm/W)
BXEX-27G-11H-3A1-00-0-0	2700	90	700	2.7	2.9	3.1	195	2.0	96
BXEX-30G-11H-3A1-00-0-0	3000	90	700	2.7	2.9	3.1	200	2.0	99
BXEX-35G-11H-3A1-00-0-0	3500	90	700	2.7	2.9	3.1	214	2.0	105
BXEX-40G-11H-3A1-00-0-0	4000	90	700	2.7	2.9	3.1	230	2.0	113
BXEX-50G-11H-3A1-00-0-0	5000	90	700	2.7	2.9	3.1	230	2.0	113
BXEX-68G-11H-3A1-00-0-0	6800	90	700	2.7	2.9	3.1	214	2.0	105

#### Notes for Tables 1 & 2:

- 1. The last 6 characters (including hyphens '-') refer to flux bins, forward voltage bins, and color bin options, respectively. "00-0-0" denotes the full distribution of flux, forward voltage, and color bin.
  - Example: BXEX-30G-11H-3A1-00-0-0 refers to the full distribution of flux, forward voltage, and color within a 3000K 3-step ANSI standard chromaticity region with a minimum of 90CRI, 1x1 die configuration, high power, 3.0V typical forward voltage.
- 2. Product CCT is hot targeted at Tsp = 85°C. Nominal CCT as defined by ANSI C78.377-2011.
- 3. Listed CRIs are minimum values and include test tolerance.
- 4. Products tested under pulsed condition (10ms pulse width) at nominal drive current.
- 5. Bridgelux maintains a ±7.5% tolerance on luminous flux measurements, ±0.15V tolerance on forward voltage measurements, and ±2 tolerance on CRI measurements for the SMD 3535.
- 6. Refer to Table 5 and Table 6 for Bridgelux SMD 3535 Luminous Flux Binning and Forward Voltage Binning information.
- 7. Typical pulsed test performance values are provided as reference only and are not a guarantee of performance.
- 8. Typical performance is estimated based on operation under pulsed current with LED emitter mounted onto a heat sink with thermal interface material and the solder point temperature maintained at 25°C. Based on Bridgelux test setup, values may vary depending on the thermal design of the luminaire and/or the exposed environment to which the product is subjected.

# **Electrical Characteristics**

**Table 3:** Electrical Characteristics

	Forward Voltage (V) <sup>2,3</sup> Drive Current			Typical Temperature Coefficient	Typical Thermal Resistance	
Part Number ¹	(mA)	Minimum Typical M		Maximum	of Forward Voltage ∆V <sub>+</sub> /∆T (mV/°C)	Junction to Solder Point⁴ R <sub>j-sp</sub> (°C/W)
BXEX-xxG-11H-3A1-00-0-0	700	2.80	3.00	3.20	-2.0 to -4.0	3.0

### Notes for Table 3:

<sup>1.</sup> Bridgelux maintains a tolerance of ± 0.15V on forward voltage measurements. Voltage minimum and maximum values at the nominal drive current are guaranteed by 100% test.

<sup>2.</sup> Products tested under pulsed condition (10ms pulse width) at nominal drive current where Tsp = 25°C.

<sup>3.</sup> Thermal resistance value was calculated using total electrical input power; optical power was not subtracted from input power.

# Absolute Maximum Ratings

Table 4: Maximum Ratings

Parameter	Maximum Rating				
LED Junction Temperature (T <sub>j</sub> )	150°C				
Storage Temperature	-40°C to +105°C				
Operating Solder Point Temperature (T <sub>Sp</sub> )	-40°C to +105°C				
Soldering Temperature	260°C or lower for a maximum of 40 seconds				
Maximum Drive Current	1500mA				
Maximum Reverse Voltage²	-				
Moisture Sensitivity Rating	MSL3				
Electrostatic Discharge	8kV HBM. JEDEC-JS-001-HBM and JEDEC-JS-001-2012				

### Notes for Table 4:

<sup>1.</sup> Bridgelux recommends a maximum duty cycle of 10% and pulse width of 10 ms when operating LED SMD at maximum peak pulsed current specified. Maximum peak pulsed current indicate values where LED SMD can be driven without catastrophic failures.

<sup>2.</sup> Light emitting diodes are not designed to be driven in reverse voltage and will not produce light under this condition. no rating is provided.

## **Product Bin Definitions**

Table 5 lists the standard photometric luminous flux bins for Bridgelux SMD 3535 LEDs. Although several bins are listed, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all CCTs.

**Table 5:** Luminous Flux Bin Definitions at 700mA,  $T_{\rm sp}$ =85 $^{\circ}$ C

Bin Code	Minimum	Maximum	Unit	Condition
D3	190	210		
D4	210	230	lm	I <sub>F</sub> =700mA
D <sub>5</sub>	230	250		

### Note for Table 5:

1. Bridgelux maintains a tolerance of  $\pm$  7.5% on luminous flux measurements.

**Table 6:** Forward Voltage Bin Definition at 700mA,  $T_{\rm sp}$ =85°C

Bin Code	Minimum	Maximum	Unit	Condition
Н	2.5	2.7		
J	2.7	2.9	V	1 700m A
K	2.9	3.1	V	I <sub>F</sub> =700mA
L	3.1	3.3		

#### Note for Table 6:

1. Bridgelux maintains a tolerance of ± 0.1V on forward voltage measurements.

# **Product Bin Definitions**

**Table 7:** MacAdam Ellipse Color Bin Definitions

сст	Color Space	Cente	r Point	Major Axis	Minor Axis	Ellipse Rotation	Color Bin	
331	Cotor space	Х	Υ	Major Axis	MINOLAXIS	Angle	COLOT BIII	
	2 SDCM	0.4653	0.4041	0.00540	0.00280	53.70	2	
2700K	3 SDCM	0.4653	0.4041	0.00810	0.00420	53.70	C/D	
20001/	2 SDCM	0.4403	0.3990	0.00556	0.00272	53.22	2	
3000K	3 SDCM	0.4403	0.3990	0.00834	0.00408	53.22	C/D	
	2 SDCM	0.4081	0.3835	0.00618	0.00276	54.00	2	
3500K	3 SDCM	0.4081	0.3835	0.00927	0.00414	54.00	C/D	
	2 SDCM	0.3762	0.3696	0.00626	0.00268	53.72	2	
4000K	3 SDCM	0.3762	0.3696	0.00939	0.00402	53.72	C/D	
	2 SDCM	0.3503	0.3589	0.00548	0.00236	59.62	2	
5000K	3 SDCM	0.3503	0.3589	0.00822	0.00354	59.62	C/D	
60001/	2 SDCM	0.3095	0.323	0.00446	0.00190	58.57	2	
6800K	3 SDCM	0.3095	0.323	0.00669	0.00285	58.57	3	

Cut_Line	2700K		3000K		3500K		4000K		5000K	
Cut_Line	Х	Υ	Х	Υ	Х	Υ	Х	Υ	Х	Υ
	0.4600	0.4031	0.4347	0.3971	0.4020	0.3804	0.3699	0.3658	0.3452	0.3548
xxG-Left	0.4618	0.4035	0.4366	0.3978	0.4040	0.3814	0.3720	0.3671	0.3469	0.3561
C Dialat	0.4690	0.4052	0.4441	0.4005	0.4121	0.3853	0.3804	0.3722	0.3537	0.3619
xxG-Right	0.4708	0.4056	0.4459	0.4011	0.4141	0.3863	0.3825	0.3735	0.3555	0.3632

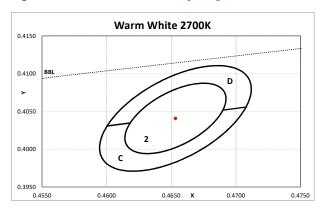
Notes for Table 7:

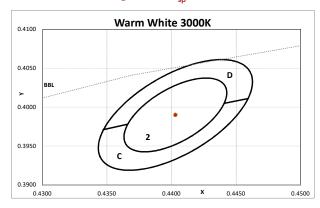
<sup>1.</sup> Color binning at  $T_{sp}$ =85 $^{\circ}$ C unless otherwise specified

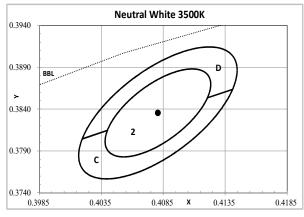
<sup>2.</sup> Bridgelux maintains a tolerance of ± 0.007 on x and y color coordinates in the CIE 1931 color space.

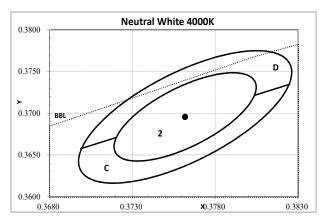
# **Product Bin Definitions**

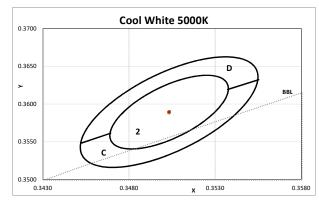
Figure 1: C.I.E. 1931 Chromaticity Diagram (3  $^{\prime}2$  Color Bin Structure, Hot-color Targeted at T $_{\rm sp}$ =85°C)

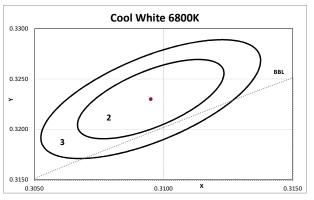












## Performance Curves

Figure 2: Drive Current vs. Forward Voltage ( $T_{\rm sp}$ =85°C)

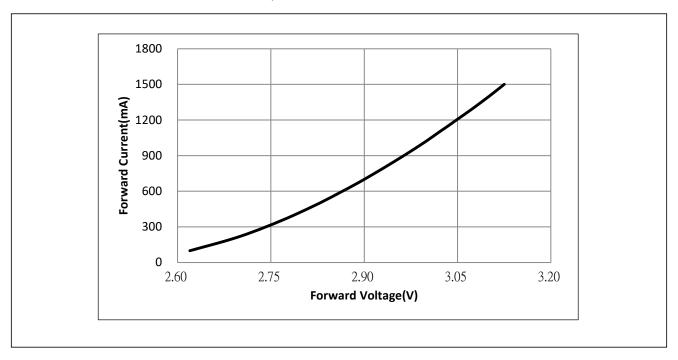
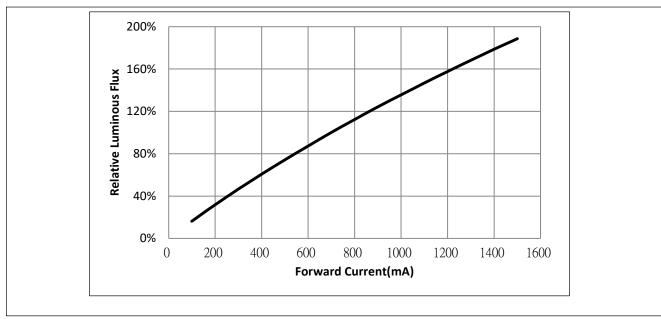


Figure 3: Typical Relative Luminous Flux vs. Forward Current ( $T_{\rm sp}$ =85°C)



Note for Figure 3:

1. Pulse width modulation (PWM) is recommended for dimming effects.

## Performance Curves

Figure 4: Typical Relative Flux vs. Solder Point Temperature

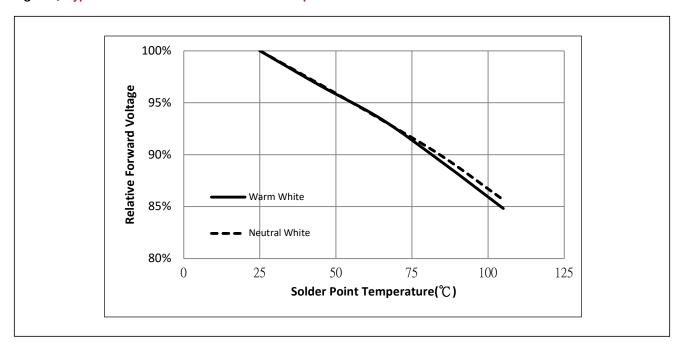
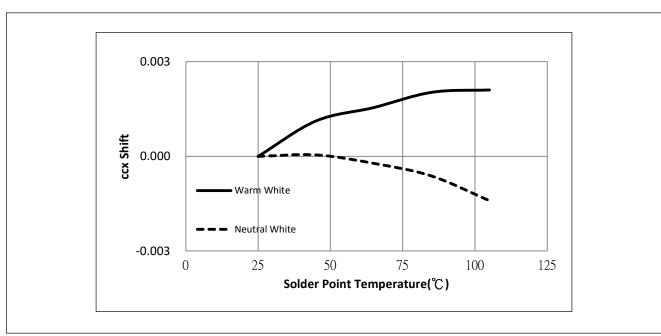


Figure 5: Typical ccx Shift vs. Solder Point Temperature



Notes for Figures 4 & 5:

- 1. Characteristics shown for warm white based on 2700K and 90 CRI.
- 2. Characteristics shown for neutral white based on 4000K and 90 CRI.
- 3. For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information

## Performance Curves

0.000
-0.004
-0.008
-0.012
-0.016
0
25
Solder Point Temperature(°C)

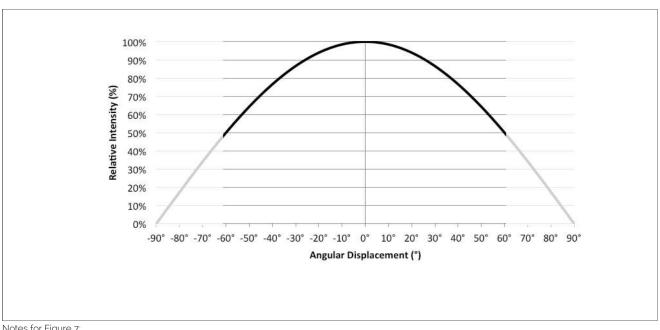
Figure 6: Typical ccy Shift vs. Solder Point Temperature

Notes for Figure 6:

- 1. Characteristics shown for warm white based on 2700K and 90 CRI.
- 2. Characteristics shown for neutral white based on 4000K and 90 CRI.
- 3. For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information

# Typical Radiation Pattern

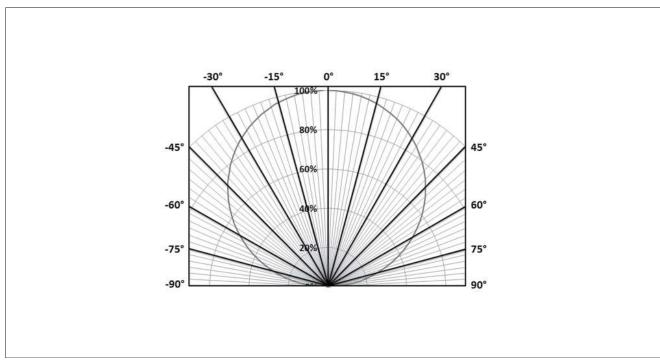
Figure 7: Typical Spatial Radiation Pattern at 700mA,  $T_{\rm sp}$ =25°C



Notes for Figure 7:

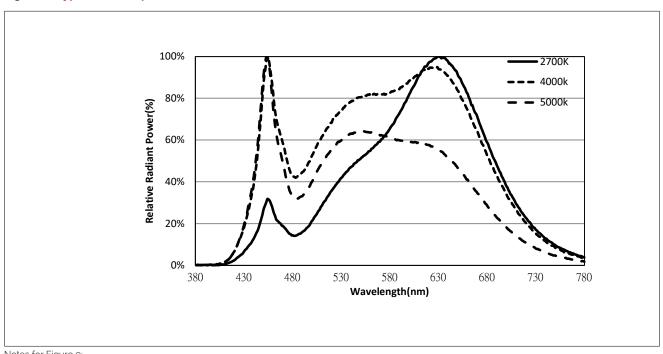
- 1. Typical viewing angle is 120°.
- 2. The viewing angle is defined as the off axis angle from the centerline where luminous intensity (Iv) is ½ of the peak value.

Figure 8: Typical Polar Radiation Pattern at 700mA,  $T_{sp}$ =25°C



# Typical Color Spectrum

Figure 9: Typical Color Spectrum

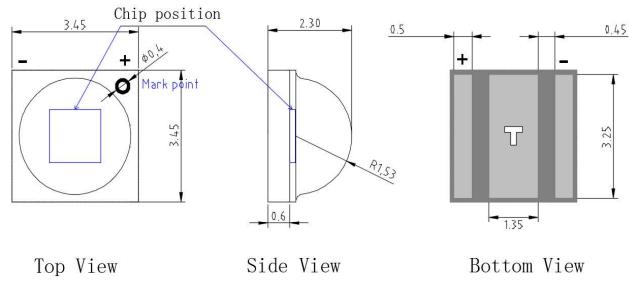


Notes for Figure 9:

- 1. Color spectra measured at nominal current for Tsp = 85°C
- 2. Color spectra shown for 90 CRI products.

## Mechanical Dimensions

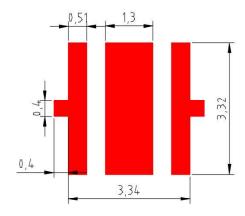
Figure 10: Drawing for SMD 3535



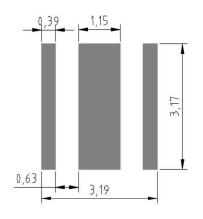
Notes for Figure 10:

- 1. Drawings are not to scale.
- 2. Drawing dimensions are in millimeters.
- 3. Unless otherwise specified, tolerances are ± 0.10mm.

## Welded plate and steel mesh Dimensions



Welded plate Dimensions



Steel mesh Dimensions

# Reliability

Table 8: Reliability Test Items and Conditions

No.	ltems	Reference Standard	Test Conditions	Drive Current	Test Duration	Units Failed/Tested
1	Moisture/reflow Sensitivity	J-STD-020E	T <sub>sld</sub> = 260°C, 10sec, Precondition: 85°C, 60%RH, 168hr		3 reflows	0/20
2	Low Temperature Storage	JESD22-A119	T <sub>a</sub> =-40°C		1000 hours	0/20
3	High Temperature Storage	JESD22-A103D	T <sub>a</sub> =105°C		1000 hours	0/20
4	Low Temperature Operating Life	JESD22-A108D	T <sub>a</sub> =-40°C	700mA	1000 hours	0/20
5	Temperature Humidity Operating Life	JESD22-A101C	T <sub>sp</sub> =85°C, RH=85%	700mA	1000 hours	0/20
6	High Temperature Operating Life	JESD22-A108D	T <sub>sp</sub> =105°C	700mA	1000 hours	0/20
7	Thermal Shock	JESD22-A106B	T <sub>a</sub> =-40°C ~100°C; Dwell : 15min; Transfer: 10sec		200 Cycle	0/20
8	Temperature Cycle	JESD22-A104E	T <sub>a</sub> =-40°C ~100°C; Dwell at extreme temperature: 15min; Ramp rate < 105°C/min		200 Cycle	0/20
9	Electrostatic Discharge	JS-001-2012	HBM, 8KV, 1.5kΩ, 100pF, Alternately positive or negative			0/20

## Passing Criteria

Item	Symbol	Test Condition	Passing Criteria
Forward Voltage	Vf	700mA	ΔVf<10%
Luminous Flux	Fv	700mA	ΔFv<30%
Chromaticity Coordinates	(x, y)	700mA	Δu'v'<0.007

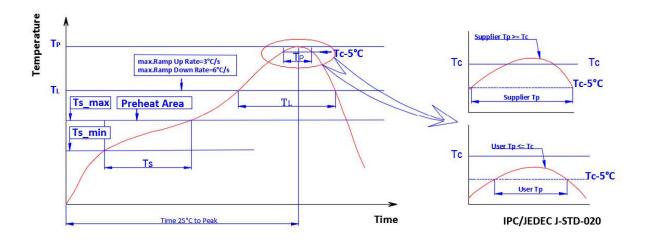
Notes for Table 8:

 $<sup>{\</sup>bf 1}.$  Measurements are performed after allowing the LEDs to return to room temperature

<sup>2.</sup>  $T_{sld}$  : reflow soldering temperature;  $T_{a}$  : ambient temperature

# **Reflow Characteristics**

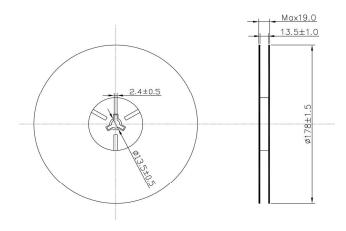
Figure 11: Reflow Profile



Profile Feature	Lead Free Assembly
Temperature Min. (Ts_min)	160°C
Temperature Max. (Ts_max)	205°C
Time (ts) from Ts_min to Ts_max	60-150 seconds
Ramp-Up Rate (TL to Tp)	3 °C/second
Liquidus Temperature (TL)	220 °C
Time (TL) Maintained Above TL	60-150 seconds
Peak Temp( Tp)	260 °C max.
Time (Tp) Within 5 °C of the Specified Classification Temperature (Tc)	25 seconds max.
Ramp-Down Rate (Tp to TL)	5 °C/second max.
Time 25 °C to Peak Temperature	10 minutes max.

# Packaging

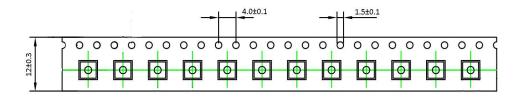
Figure 12: Emitter Reel Drawings

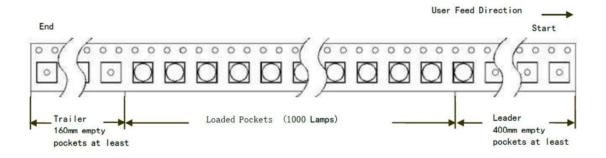


Note for Figure 12:

1. Drawings are not to scale. Drawing dimensions are in millimeters.

Figure 13: Emitter Tape Drawings





Note for Figure 13:

<sup>1.</sup> Drawings are not to scale. Drawing dimensions are in millimeters.

# Packaging

Figure 14: Emitter Reel Packaging Drawings



E1E015/1

Note for Figure 14:

1. Drawings are not to scale.

# **Design Resources**

Please contact your Bridgelux sales representative for assistance.

## **Precautions**

### **CAUTION: CHEMICAL EXPOSURE HAZARD**

Exposure to some chemicals commonly used in luminaire manufacturing and assembly can cause damage to the LED emitter. Please consult Bridgelux Application Note AN51 for additional information.

#### **CAUTION: EYE SAFETY**

Eye safety classification for the use of Bridgelux SMD LED emitter is in accordance with IEC specification EN62471: Photobiological Safety of Lamps and Lamp Systems. SMD LED emitters are classified as Risk Group 2 when operated at or below the maximum drive current. Please use appropriate precautions. It is important that employees working with LEDs are trained to use them safely.

### **CAUTION: RISK OF BURN**

Do not touch the SMD LED emitter during operation. Allow the emitter to cool for a sufficient period of time before handling. The SMD LED emitter may reach elevated temperatures such that could burn skin when touched.

## **CAUTION**

#### **CONTACT WITH LIGHT EMITTING SURFACE (LES)**

Avoid any contact with the LES. Do not touch the LES of the emitter or apply stress to the LES (yellow phosphor resin area). Contact may cause damage to the emitter

Optics and reflectors must not be mounted in contact with the LES (yellow phosphor resin area).

## **Disclaimers**

#### MINOR PRODUCT CHANGE POLICY

The rigorous qualification testing on products offered by Bridgelux provides performance assurance. Slight cosmetic changes that do not affect form, fit, or function may occur as Bridgelux continues product optimization.

#### STANDARD TEST CONDITIONS

Unless otherwise stated, LED emitter testing is performed at the nominal drive current.

# About Bridgelux: Bridging Light and Life™

At Bridgelux, we help companies, industries and people experience the power and possibility of light. Since 2002, we've designed LED solutions that are high performing, energy efficient, cost effective and easy to integrate. Our focus is on light's impact on human behavior, delivering products that create better environments, experiences and returns—both experiential and financial. And our patented technology drives new platforms for commercial and industrial luminaires.

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